



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-20
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CRO7*UD72EC6	A	SH1A	2016-06-20
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	Package: 07 SO 08 .15 JEDEC; MDF valid for L5972D013TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CRO7*UD72EC6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.023	mg	supplier	die	Silicon (Si)	7440-21-3		4.792	mg	954012	59900
				supplier	metallization	Aluminium (Al)	7429-90-5		0.032	mg	6371	400
				supplier	metallization	Tungsten (W)	7440-33-7		0.050	mg	9954	625
				supplier	Passivation	Silicon Nitride	12033-89-5		0.008	mg	1593	100
				supplier	Passivation	Silicon Oxide	7631-86-9		0.074	mg	14732	925
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	597	38
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.024	mg	4778	300
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.003	mg	597	38
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.037	mg	7366	463
				Leadframe	Copper & its alloys	32.113	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.732	mg	22795	9150
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.044	mg	1370	550
supplier	alloy	Zinc (Zn)	7440-66-6						0.038	mg	1183	475
supplier	metallization	Nickel (Ni)	7440-02-0						0.151	mg	4702	1888
supplier	metallization	Palladium (Pd)	7440-05-3						0.005	mg	156	63
supplier	metallization	Gold (Au)	7440-57-5						0.005	mg	156	63
supplier	metallization	Silver (Ag)	7440-22-4						0.005	mg	156	63
supplier	glue	Silver (Ag)	7440-22-4						1.164	mg	879819	14550
supplier	glue	Isobornyl Methacrylate	7534-94-3						0.066	mg	49887	825
supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.066	mg	49887	825				
supplier	glue	Acrylate polymer	87320-05-6		0.027	mg	20408	338				
Bonding wires	Other inorganic materials	0.110	mg	supplier	wire	Copper (Cu)	7440-50-8		0.110	mg	1000000	1375
Encapsulation	Other Organic Materials	41.431	mg	supplier	mold compound	Silica, vitreous	60676-86-0		35.879	mg	865994	448488
				supplier	mold compound	Epoxy Resin	Proprietary		3.107	mg	74992	38838
				supplier	mold compound	Phenol Resin	Proprietary		2.072	mg	50011	25900
				supplier	mold compound	Carbon black	1333-86-4		0.207	mg	4996	2588
supplier	mold compound	Bismuth compound	7440-69-9		0.166	mg	4007	2075				